Title (en)

Method of manufacturing copper alloy containing active metal

Title (de)

Verfahren zur Herstellung von einer aktives metallenthaltenden Kupferlegierung

Title (fr)

Procédé de production d'un alliage de cuivre contenant un métal actif

Publication

EP 0717119 A3 19960821 (EN)

Application

EP 95307543 A 19951024

Priority

JP 26044794 A 19941025

Abstract (en)

[origin: EP0717119A2] When a copper alloy containing a metal more reactive with oxygen than copper is melted and cast, a feedstock is vacuum melted with an induction melting furnace (4) within an airtight container (5) which has been vacuum evacuated, and thereafter positive pressure is applied (via pipe 26) to the airtight container (5), and the molten metal is discharged from the furnace through a pouring siphon (32) for continuously casting in a mold (51). Said positive pressure is exerted using an inert gas. <IMAGE>

IPC 1-7

C22C 1/02; C22C 9/00

IPC 8 full level

B22D 11/10 (2006.01); **B22D 11/103** (2006.01); **C22B 9/04** (2006.01); **C22C 1/02** (2006.01)

CPC (source: EP)

B22D 11/103 (2013.01); **B22D 11/113** (2013.01); **B22D 41/05** (2013.01); **C22C 1/02** (2013.01)

Citation (search report)

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- [A] PATENT ABSTRACTS OF JAPAN vol. 9, no. 256 (M - 421) 15 October 1985 (1985-10-15)
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Designated contracting state (EPC)

DE

DOCDB simple family (publication)

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